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Complete if Known

Application Number	Not Yet Assigned
Filing Date	June 23, 2003
First Named Inventor	Mitsuru SEKIGUCHI
Art Unit	2813
Examiner Name	Not Yet Assigned

Attorney Docket Number

740819-1014

U.S. PATENT DOCUMENTS

Examiner Initials ¹	Cite No. ¹	U.S. Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)	Kind Code ² (if known)			
		US-6,181,012 B1		01/30/2001	Edelstein et al	
		US-6,242,808 B1		06/05/2001	Shimizu et al	
		US-6,123,825		09/26/2000	Uzoh et al	
		US-6,130,156		10/10/2000	Havemann et al	
		US-				
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FOREIGN PATENT DOCUMENTS

Examiner Initials ¹	Cite No. ¹	Foreign Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁴
		Country Code ³ Number ⁴	Kind Code ² (if known)				
		JP 02-114639 A		04/26/1990	Seiichi		W/Abstract

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials ¹	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		P.J. Ding et al., "Oxidation resistant high conductivity copper films", Appl. Phys. Lett. 64, No. 21, pp. 2897-2899, May 23, 1994	
		C Ryu et al., "Effect of Texture on the Electromigration of CVD Copper", IEEE, pp. 201-205, 1997	
		M. Hasunuma et al., "Copper Reflow Process With Redox Cycle Reaction", The 42 nd Spring Meeting of the Japan Society of Applied Physics, No. 2, p. 810, 30a-K-6, March 1995, with English Translation	

Examiner Signature

Date Considered

3/17/04

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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